intel

AUGUST 2023

Meteor Lake Architecture Overview

Advancing Moore's Law 5 NODES IN 4 YEARS



Build our most **power-efficient** client processor in history

Deliver **AI at Scale** First client integration of AI engine (NPU)

Leap in **graphics** performance With increased power efficiency

Launch IA on Intel 4 First Intel 4 P-core (Redwood Cove) & Ecore (Crestmont)

Meteo

Lake

Pillars









SOC Tile

New **low power island** E-cores

First built-In NPU AI Engine

Leading Wi-Fi 6E & Wi-Fi 7 support

8K HDR & leading AV1 support

Native HDMI 2.1 and DP 2.1 standards

Integrated memory controller & DDR



Compute Tile

New **E-core** microarchitecture

New P-core microarchitecture

First on Intel 4 process technology



Intel Tech Tour: Meteor Lake





Intel[®] Arc[™] graphics only available on select MTL processor-powered systems with dualchannel memory.

IO Tile

Industry leading connectivity with integrated **Thunderbolt 4** & PCIe Gen5

Thunderbolt 4 PCIe Gen 5





Industry leading FOVEROS 3D packaging

Intel Tech Tour: Meteor Lake

Next-gen Uncore Guiding Principles Repartition compute intensive IPs for **power optimization**

Enable IO bandwidth scalability

Extend hybrid architecture with the addition of **low power** IA cores

Re-construct power management

Repartition Compute Intensive IP

Media IP is embedded in graphics IP

Media



Graphics

Complex



Repartition Compute Intensive IP

Media IP is embedded in graphics IP

Graphics attached to core complex

Core Complex Graphics Complex ╡║╟┽┽╧╼╼╧┥┥┥╸

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Prior Gen

Repartition Compute Intensive IP

Media IP is embedded in graphics IP

Graphics attached to core complex

All use same ring fabric

Ring fabric only way to access mem



Prior Gen



Prior Gen

Repartition Compute Intensive IP

Core complex stays on if either graphics or media need to access memory



Media separated from graphics







Media separated from graphics

Both independently attached to SOC

Independent core complex

Graphics Tile Media

Media separated from graphics

Both independently attached to SOC

Independent core complex

All IPs have independent paths to memory





Media separated from graphics

Both independently attached to SOC

Independent core complex

All IPs have independent paths to memory

All IPs can be independently powered on/off







I/O Bandwidth Scalability

Media/Graphics/NPU/IO tile add significant traffic

IO Port now critical bottleneck



I/O Bandwidth Scalability		Graphics _{Tile}	
Media/Graphics/NPU/IO tile add significant traffic IO Port now critical bottleneck Custor Side Chann	m el	Media	
SOLUTION #1 Custom side channels for each IP Not scalable	IO Tile	Image Compute Tile	Custom Side Channel

I/O Bandwidth Scalability

Media/Graphics/NPU/IO tile add significant traffic

IO Port now critical bottleneck

CHOSEN SOLUTION

New Scalable Fabric for high BW (128 GBs) connectivity

All IO ordering and address translation goes through IOC





Next Evolution of Our Hybrid Architecture

OPPORTUNITY

IA complex is woken up even for low compute intensity workloads



Next Evolution of Our Hybrid Architecture

OPPORTUNITY

IA complex are woken up even for low compute intensity workloads

SOLUTION

Lower power E-cores on SOC

	Graphics ^{Tile}	
	Media Pape E-cores	
Display C	Image	
I O Tile	Compute	

Re-constructing Power Management

Grounds up **modular and scalable PM** architecture for disaggregation

New scalable fabric for improved bandwidth and energy efficiency

Coordination between **multiple PM controllers** on different tiles

Coordination between SOC PM controllers and system software



Next-gen Uncore Guiding Principles

Repartition compute intensive IPs for **power optimization**

Enable IO bandwidth scalability

Re-design of hybrid architecture with the addition of **low power** IA cores

Re-construct Power Management





New Architectural Capabilities

AI is Everywhere

INTRODUCING

Intel's First Integrated NPU

Dedicated AI Engine for Low Power Inference

Purpose built for efficient client Al

Ideal for sustained Al and Al offload

Standardized program interfaces

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Embargoed Until: Sept 19th, 9 a.m. PST (12 p.m. EST)



Performance Parallelism & Throughput

Ideal for Al infused in Media/3D/render pipeline

Dedicated Low Power Al Engine

Ideal for sustained AI and AI offload

Fast Response

Ideal for light-weight, single inference low-latency AI tasks

Powered By Meteor Lake



Graphics IP

Scaling the graphics engine

Performance Capability



Power

 $\ensuremath{^*\text{See}}$ appendix for workloads and configurations. Results may vary.

Meteor Lake GPU



**Intel® Arc™ graphics only available on select MTL processor-powered systems with dual-channel memory.

Performance Hybrid Architecture



*Conceptual representation of 3D Perf Hybrid Arch

INTEL THREAD DIRECTOR

Architecture

OS Scheduler

Intel Thread Director

E-cores & P-cores

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Leveraging Disaggregation

Leveraging

Disaggregation

"Experience First" Client drives New Era of System level integration

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Leveraging

Disaggregation

"Experience First" Client drives New Era of System level integration **Process, packaging & architecture** together make this possible

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Leveraging

Disaggregation

"Experience first" client drives new era of system-level integration **Process, packaging & architecture** together make this possible **Extremely flexible architecture** that scales across design points and time

FOVEROS TECHNOLOGY ADVANTAGE

Energy Efficient pJ/Bit

Low Latency Nanosecond/trip **Through Silicon Via** For power delivery and off-package I/O

Fine micro-bumps Optimized for dense 3D and low power **C4 connection** Silicon to package standard

High

Density

Wires / Area

Introducing

Intel 4 Logic process technology

area scaling for High Perf Logic library vs Intel 7*

2x

EUV lithography for process simplification

>20% power efficiency vs Intel 7* Compatible with **3D Foveros** Advanced Packaging

> *Based on internal estimates. Learn more at www.intel.com/PerformanceIndex. Results may vary.

Build our most **power-efficient**

client processor in history



Launch IA on Intel 4

First Intel 4 P-core (Redwood Cove) & E-core (Crestmont)



Leap ahead on **graphics** Up to 2x GFX performance/watt*

Deliver Al at Scale

First client integration of AI engine (NPU)

*Compared to prior generation. See appendix for more information. Results may vary

Neteor Lake

Most power-efficient processor we've ever built



Meteor Lake

New **P-core & E-core** microarchitectures





3D Performance Hybrid Architecture





FOVEROS 3D packaging Latest **Media & Display** Standards







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Thunderbolt 4

First on Intel 4

intel[™] ARC[™]

Power efficiency & Al at scale

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Performance results are based on testing as of dates shown in configurations and may not reflect all publicly available updates. See backup for configuration details.

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